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HIGH CURRENT, HIGH DENSITY, ISOLATED, SILICON POWER RECTIFIER STUD

QUICK REFERENCE DATA

- Low thermal impedance
- Small size and low weight
- High current applications
- Isolated for direct heatsink mounting
- High surge ratings

- $V_R = 150V - 1000V$
- $I_F = 15A$
- $t_{rr} = 30nS - 2\mu S$
- $I_{FSM} \geq 150A$

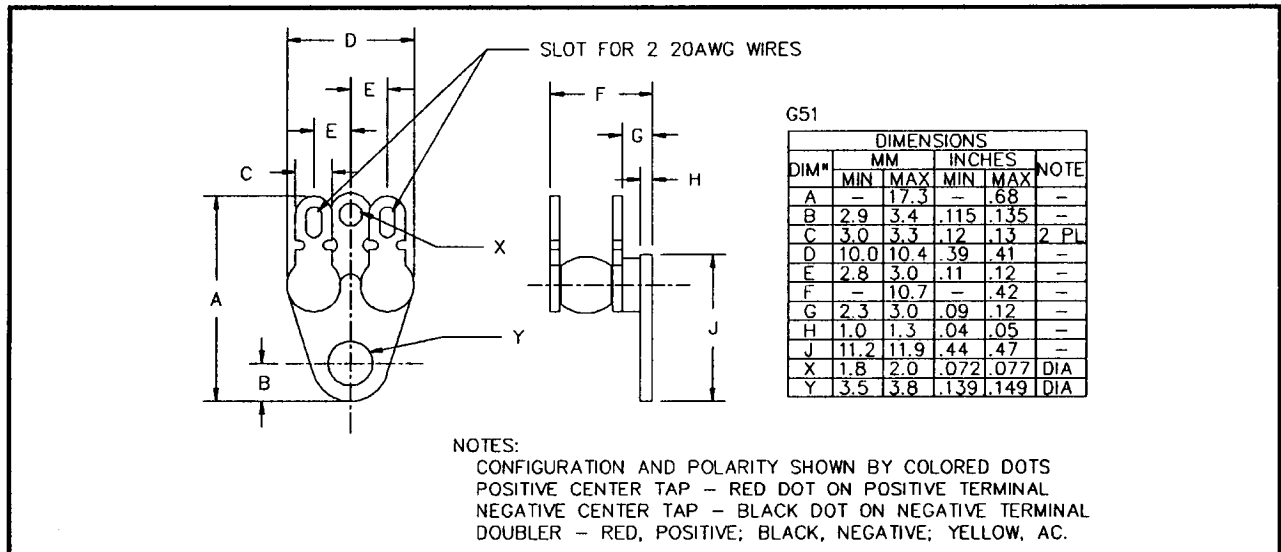
ABSOLUTE MAXIMUM RATINGS

Device Type	Working Reverse Voltage	Average Rectified Current $I_{F(AV)}$ @ T_{MB} see note 1			1 Cycle Surge I_{FSM} @ $t_p = 8.3ms$		Operating & Storage Temperature Range	
		@ 55°C	100°C	125°C	@ 25 °C	@ 100°C	(Top) (Tstc)	
		Volts	Amps	Amps	Amps	Amps	Amps	°C
SET03**03	1000	30	22	16	150	100	-55 to +175	
SET03**19	1000	20	16	12	150	80	-55 to +175	
SET03**12	600	30	22	16	150	100	-55 to +175	
SET03**04	400	30	22	16	150	80	-55 to +175	
SET03**11	150	30	20	14	175	175	-55 to +150	

1/ Average Rectified Current = $0.5 \times I_{F(AV)}$ for Doubler

$R_{\theta JMB} = 1.5^\circ C/W$ for all varieties, see next page for circuit configurations.

MECHANICAL



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ELECTRICAL CHARACTERISTICS (Apply per leg)

Device Type	Maximum Leakage Current @ V_{RWM}		Maximum Forward Voltage @ 9.0 A	Maximum Reverse Recovery Time
	$T_j = 25\text{ }^\circ\text{C}$	$T_j = 100\text{ }^\circ\text{C}$		
	μA	μA	Volts	nS
SET03**03	1.0	20	1.2	2000
SET03**19	1.0	25	2.2	150
SET03**12	1.0	20	1.2	2000
SET03**04	1.0	20	1.5	150
SET03**11	10.0	500	1.1	30

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CIRCUIT CONFIGURATIONS

** = 06 Positive Center Tap

** = 08 Negative Center Tap

** = 10 Doubler

eg. SET030603 = Positive Center Tap
1000V, 2000nS

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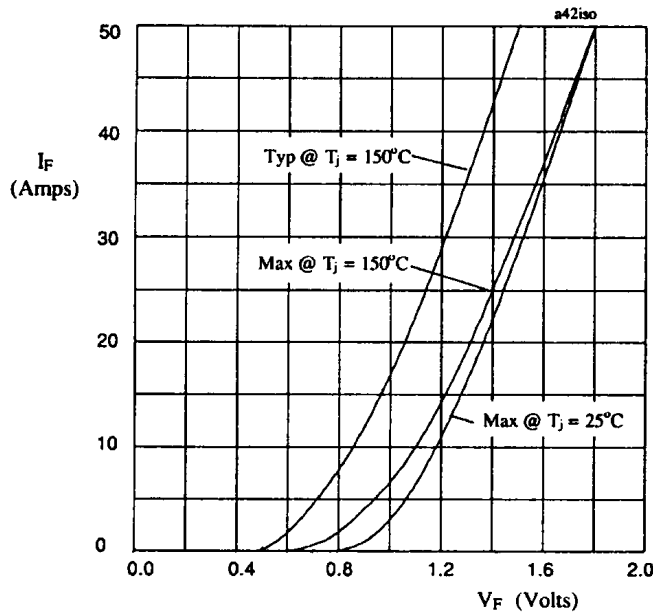


Figure 1. Forward voltage drop as a function of forward current for SET03**03 & SET03**12.

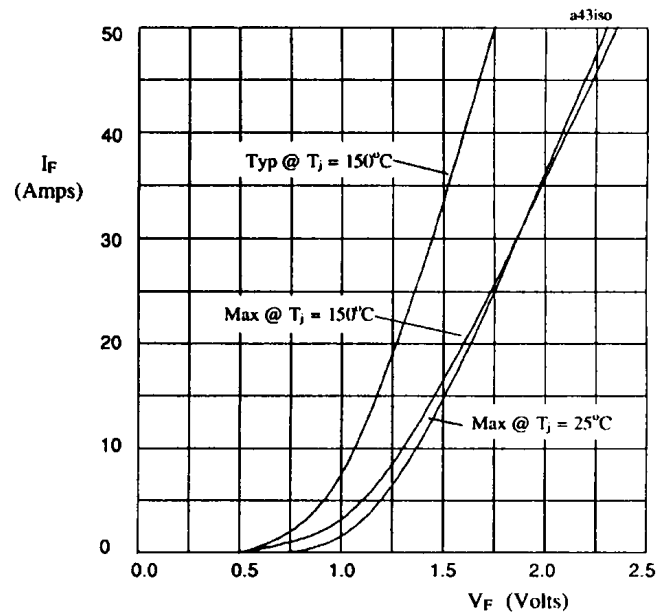


Figure 2. Forward voltage drop as a function of forward current for SET03**04.

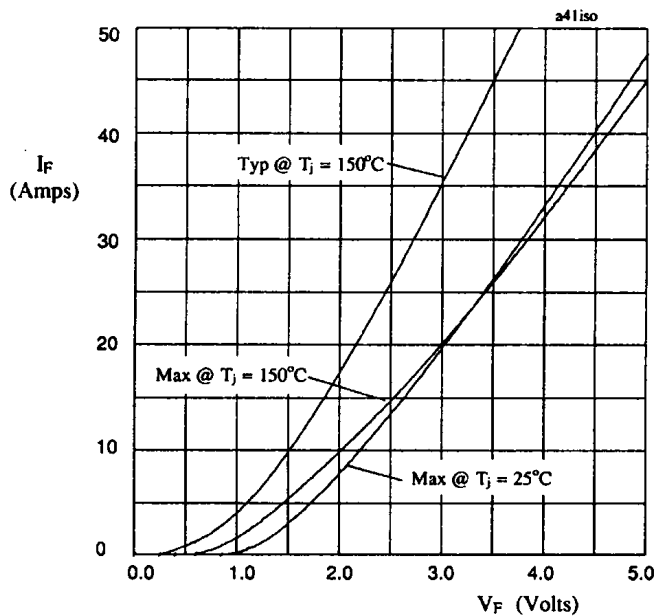


Figure 3. Forward voltage drop as a function of forward current for SET03**19.

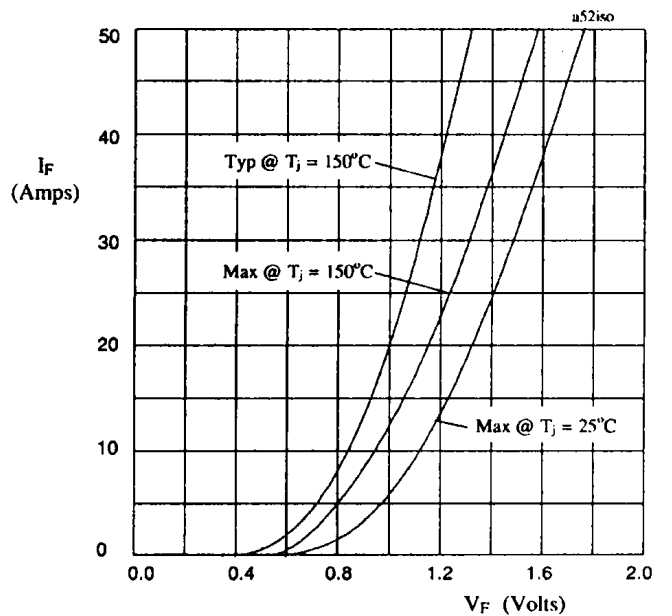


Figure 4. Forward voltage drop as a function of forward current for SET03**11.

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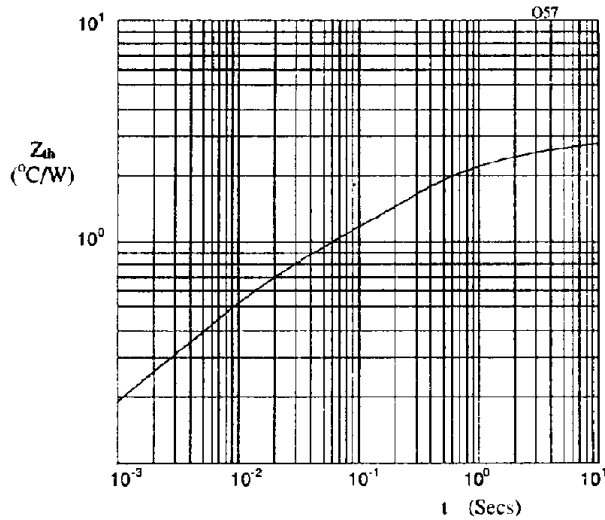


Figure 5. Typical transient thermal impedance characteristic.

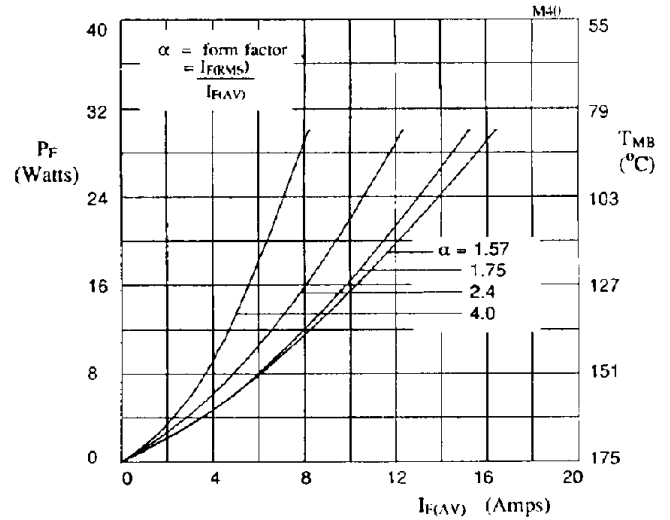


Figure 6. Forward power dissipation and maximum allowable mounting base temperature as a function of forward current for sinusoidal operation, for SET03**03 and SET03**12.

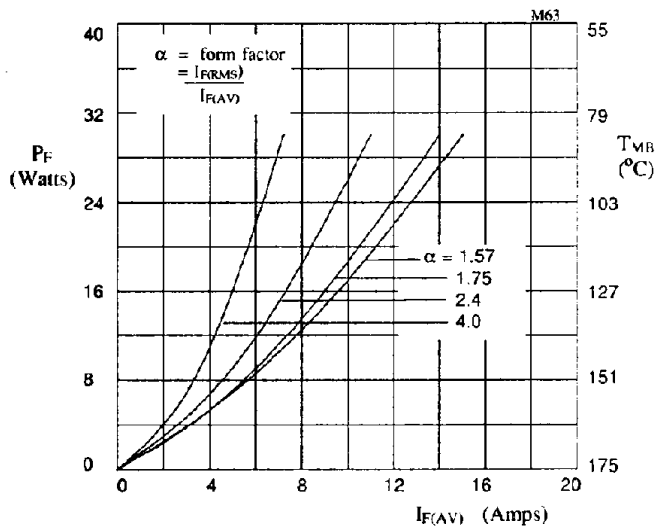


Figure 7. Forward power dissipation and maximum allowable mounting base temperature as a function of forward current for sinusoidal operation, for SET03**04.

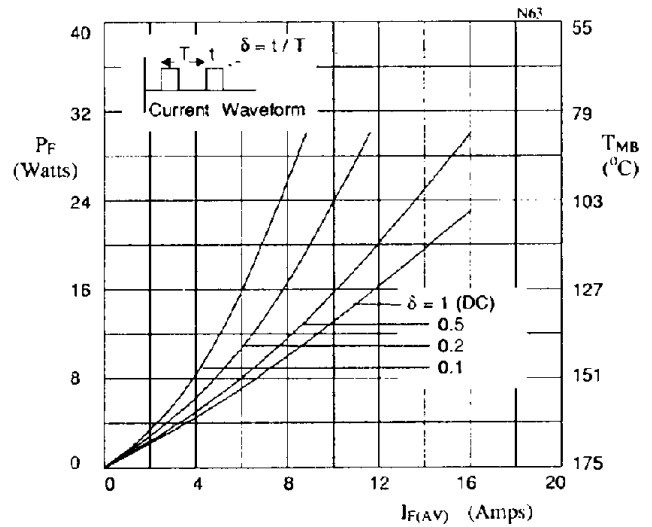


Figure 8. Forward power dissipation and maximum allowable mounting base temperature as a function of forward current for square wave operation, for SET03**04

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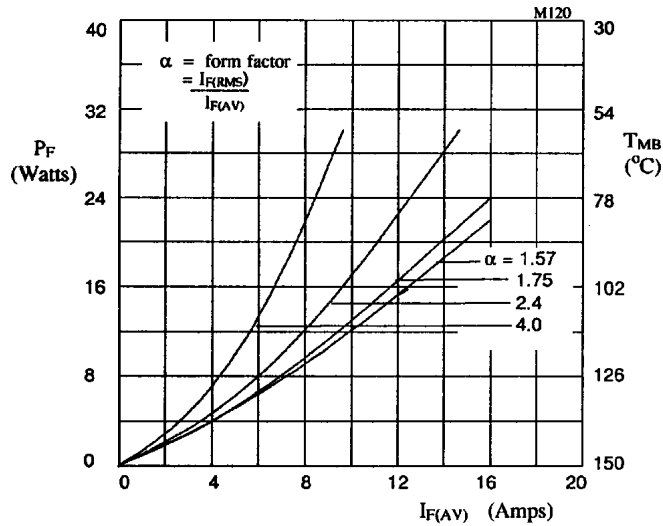


Figure 9. Forward power dissipation and maximum allowable mounting base temperature as a function of forward current for sinusoidal operation, for SET03**11.

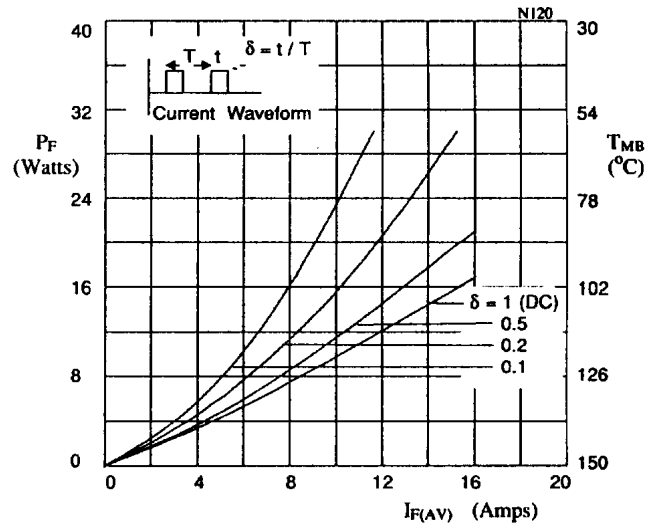


Figure 10. Forward power dissipation and maximum allowable mounting base temperature as a function of forward current for square wave operation, for SET03**11.